PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5103084

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YONG LI	05/16/2018

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION
Street Address:	18 ZHANG JIANG ROAD
Internal Address:	PUDONG NEW AREA
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201203
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION
Street Address:	18 WEN CHANG ROAD
Internal Address:	ECONOMIC-TECHNOLOGICAL DEVELOPMENT AREA, DAXING DISTRICT
City:	BEIJING
State/Country:	CHINA
Postal Code:	100176

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16021382

CORRESPONDENCE DATA

Fax Number: (312)321-4299

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 312-321-4200

Email: sdamron@brinksgilson.com, usassignments@brinksgilson.com, sbrim@brinksgilson.com, rpetitt@brinksgilson.com

Correspondent Name: BRINKS GILSON & LIONE

Address Line 1: 455 N. CITYFRONT PLAZA DRIVE

Address Line 2: SUITE 3600

Address Line 4: CHICAGO, ILLINOIS 60611

ATTORNEY DOCKET NUMBER:	15741-34 2016-01577 SH-US
NAME OF SUBMITTER:	SCOTT W. BRIM
SIGNATURE:	/Scott W. Brim/
DATE SIGNED:	08/22/2018

Total Attachments: 2
source=15741.034_Assignment#page1.tif
source=15741.034_Assignment#page2.tif

ASSIGNMENT

WHEREAS, **Yong Li**, the "Assignor", has made the invention described in the United States patent application entitled **SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREFOR**, executed by Assignor on the same date as, or on a date prior to, this Assignment;

WHEREAS, **Semiconductor Manufacturing International (Shanghai) Corporation**, a corporation organized and existing under the laws of the Country of **China**, having a place of business at **18 Zhang Jiang Road, Pudong New Area, Shanghai 201203, P.R. China**, and **Semiconductor Manufacturing International (Beijing) Corporation**, a corporation organized and existing under the laws of the Country of **China**, having a place of business at **18 Wen Chang Rd., Economic-Technological Development Area, Daxing District, Beijing 100176, P.R. China**, the "Assignees", desires to acquire the entire right, title and interest in the invention and the patent application identified above, and all patents which may be obtained for the invention, as set forth below;

NOW, THEREFORE, in consideration of valuable and legally sufficient consideration, the receipt of which by the Assignor from the Assignees is acknowledged, the Assignor has sold, assigned and transferred, and by these presents sell, assign and transfer to the Assignees, the entire right, title and interest for the United States in the invention and the patent application identified above, and any patents that may issue for the invention in the United States; with the entire right, title and interest in the invention and all patent applications and patents issuing therefrom in all countries foreign to the United States, including the full right to claim for any such application all benefits and priority rights under any applicable convention; with the entire right, title and interest in all continuations, divisions, renewals and extensions of any of the patent applications and patents defined above; with the right to recover all damages, including, but not limited to, a reasonable royalty, by reason of past, present, or future infringement or any other violation of patent or patent application rights; to have hold for the sole and exclusive use and benefit of the Assignees, its successors and assigns, to the full end of the term or terms for all such patents.

The Assignor covenants and agrees, for both the Assignor and the Assignor's legal representatives, that the Assignor will assist the Assignees in the prosecution of the patent application identified above; in the making and prosecution of any other patent applications that the Assignees may elect to make covering the invention identified above; in vesting in the Assignees exclusive title in all such other patent applications and patents; and that the Assignor will execute and deliver to the Assignees all additional papers which may be requested by the Assignees to carry out the terms of this Assignment.

The Commissioner of Patents and Trademarks is authorized and requested to issue patents to the Assignee under the terms of this Assignment.

IN TESTIMONY WHEREOF, the Assignor has executed this agreement.

DATED: 2018-5-16

李勇/Yong Li

Yong Li